



**PATENT APPLICATION
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q73159

Hien Boon TAN , et al.

Appln. No.: 10/721,384

Group Art Unit: 2826

Confirmation No.: 6008

Examiner: Alexander O. Williams

Filed: November 26, 2003

For: HIGH PERFORMANCE CHIP SCALE LEADFRAME PACKAGE AND METHOD OF
MANUFACTURING THE PACKAGE

PETITION FOR EXTENSION OF TIME UNDER 37 C.F.R. § 1.136

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Pursuant to 37 C.F.R. § 1.136, Applicant hereby petitions for an extension of time of two month(s), extending the time for responding to the Office Action of April 22, 2005 to September 22, 2005.

Please charge the statutory fee of \$450.00 to Deposit Account No. 19-4880. The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account. A duplicate copy of this sheet is enclosed.

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SUGHRUE MION, PLLC
Telephone: (202) 293-7060
Facsimile: (202) 293-7860

WASHINGTON OFFICE

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CUSTOMER NUMBER

Respectfully submitted,

Alan J. Kasper
Registration No. 25,426

Date: September 14, 2005